

## FEATURES:

- Being of the ultra-miniature SMD type, and thus featuring excellent efficiency in mounting, the CM155 is ideal for application to highdensity circuit boards.
- As it incorporates a heat-resisting packaged cylinder-type crystal, it features highly stable characteristics-high enough to permit reflow soldering.
- Can be mounted automatically because of the emboss taping used.
- Its low power consumption makes it ideal for application to portable equipment as well as high density, cellular phone designs.


## APPLICATIONS:

- Permits use as a clock source for communication equipment, AV equipment, OA equipment, camera, cellular phones, pagers and measuring instruments.
STANDARD SPECIFICATIONS

| Item |  | CM155 | Conditions |
| :---: | :---: | :---: | :---: |
| Nominal frequency | f0 | 32.768 kHz |  |
| Frequency tolerance | delta <br> f/fo | $\pm 20 \mathrm{ppm}$ | Reference temperature |
| Frequency vs.Temperature Characteristics | delta $\mathrm{f} / \mathrm{f}_{0}$ | See drawing | $-10^{\circ} \mathrm{C}$ to $+60^{\circ} \mathrm{C}$ |
| Turnover temperature | Tm | $25^{\circ} \mathrm{C} \pm 5^{\circ} \mathrm{C}$ |  |
| Freq. temp. coefficient | beta | $-0.034 \pm 0.006 \mathrm{ppm} /{ }^{\circ} \mathrm{C}_{2}$ |  |
| Operating temperature range | Topr | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ |  |
| Storage temperature range | $\mathrm{T}_{\text {stg }}$ | $-55^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$ |  |
| Equivalent series resistance | R1 | 65 k ohm MAX. | Reference temperature |
| Load capacitance | CL | 12.5 pF TYP. | Please specify |
| Motional capacitance | $\mathrm{C}_{1}$ | 0.0025 pF TYP. |  |
| Shunt capacitance | $\mathrm{C}_{0}$ | 1.0 pF TYP. |  |
| Capacitance ratio | gamma | 400 TYP. |  |
| Drive level | DL | $1 \mu \mathrm{~W}$ MAX. |  |
| Insulation resistance | IR | 500 M ohm MIN. | $\mathrm{DC} 100 \mathrm{~V} \pm 15 \mathrm{~V}$ |
| Aging (First year) | delta f/f0 | $\pm 3 \mathrm{ppm}$ MAX. | $25^{\circ} \mathrm{C} \pm 3^{\circ} \mathrm{C}$ |
| Sealing |  | $1 \times 10-2 \mu \mathrm{~Pa} \cdot \mathrm{m3} / \mathrm{s}$ MAX. |  |
| Shock resistance |  | $\pm 5 \mathrm{ppm}$ MAX. <br> Drop test of 3 times on a hard board from 75 cm height or shock test of $3000 \mathrm{G} \times 0.3 \mathrm{~ms} \times 1 / 2 \sin$ wave x 3 directions |  |

- FREQUENCY vs TEMPERATURE CURVE


■ DIMENSIONS: (UNIT=mm)


RECOMENDED SOLDERING PATTERN: (UNIT=mm)


Back

